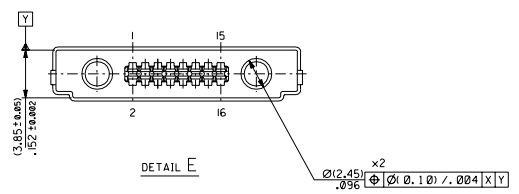
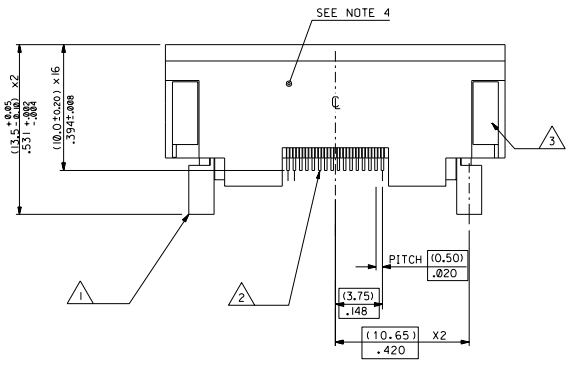
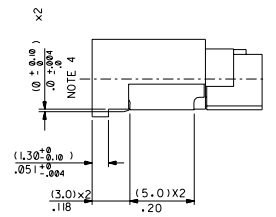
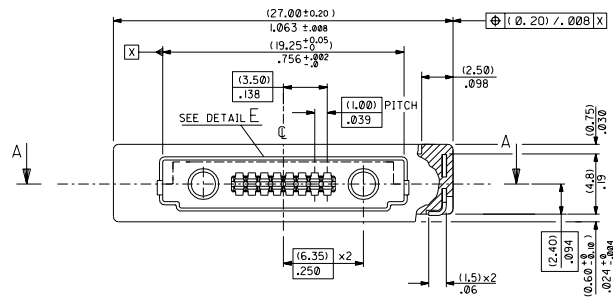


COMPONENT	PCB PAD DIMENSION	QTY
LOCKING LATCHES $\Delta 1$	(2.60) / .102 x (4.65) / .183 Φ (0.10) / .004 R	(x2)
SIGNAL CONTACTS $\Delta 2$	(0.35) / .05 / .014 ± .002 x (2.0) / .08 Φ (0.10) / .004 R	(x16)
SMT RETENTION PADS $\Delta 3$	(2.5) / .098 x (5.0) / .197 Φ (0.10) / .004 R	(x2)



NOTES:

- MATERIALS:
HOUSING: NYLON 46 50% CLASS FILLED COLOUR BLACK
SMT RETENTION PADS: PHOSPHOR BRONZE (0.30) / .012 REF. THICK.
PLATING: (3.5um) / .18 - .197um IN. TIN.
OVER (1.27um) / .050um NICKEL.
LOCKING LATCHES: PHOSPHOR BRONZE (0.30) / .012 REF. THICK.
PLATING: (3.5um) / .18 - .197um IN. TIN.
OVER (1.27um) / .050 NICKEL.
SIGNAL CONTACTS: PHOSPHOR BRONZE (0.20) / .008 REF. THICK.
PLATING: (1.27um) / .050um MIN. NICKEL UNDERCOAT OVERALL.
GOLD FLASH (0.1um) / .004um MIN.
OVER PALLADIUM NICKEL (1.0um) / .039um MIN. IN CONTACT AREA. (3.0um) / .118um MIN. TIN ON TAIL SECTION.
- MATES WITH 90813 SERIES PLUG CONNECTOR.
- SEE PRODUCT SPECIFICATION P5 99020-0045.
- ALL SMT TAILS TO LIE WITHIN A COPLANARITY BAND OF (0.0) / .0 - (0.1) / .004 REF. FROM EACH OTHER AND BELOW HOUSING BASE.
- COMPONENT PACKAGING: TO BE PACKED IN EMBOSSED TAPE. SEE SDA-90811-9001

REMOVE LEAD FROM PLATING EC NO. E2004-0574 DRAWN: DEARION 05/01/04 CHK: [] APP: []	DESCRIPTION MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE: 5:1	DESIGN UNITS: mm	DIMENSIONS: mm INCH mm INCH mm INCH		SHT	REV
		4 PLACES ±0.1	3 PLACES ±0.05	2 PLACES ±0.05	1 PLACE ±0.10	ANGULAR: ± 1/2 °	THIRD ANGLE PROJECTION		REVISE ON CAD ONLY
DRAWN BY & DATE HDU 95/03/29		CHECKED BY & DATE		APPROVED BY & DATE		TITLE: I/O CONNECTOR FOR MOBILE PHONE			
CAD FILENAME		MATERIAL NO. 90811-2001		DRAWING NO. SDA-90811-2001		SHEET NO. 10F1		MOLEX INCORPORATED	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.							